



Product Change Notification / RMES-07XGHT586

Date:

19-Jan-2022

Product Category:

OTN Processors & PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4700 Final Notice: Qualification of an additional bill of materials for PM5456A-FEI, PM5451A-FEI and PM5450A-FEI Microsemi catalog part numbers (CPN) available in 1517L BBGA (40x40x3.22mm) package at ATK assembly site.

Affected CPNs:

[RMES-07XGHT586_Affected_CPN_01192022.pdf](#)

[RMES-07XGHT586_Affected_CPN_01192022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of an additional bill of materials for PM5456A-FEI, PM5451A-FEI and PM5450A-FEI Microsemi catalog part numbers (CPN) available in 1517L BBGA (40x40x3.22mm) package at ATK assembly site.

Pre and Post Change Summary:

| | Pre Change | Post Change |
|--|------------|-------------|
|--|------------|-------------|

| | | | | |
|----------------------------|----------------------|--|--|-------|
| Assembly Site | | Amkor Technology Korea (K4), INC (ATK) | Amkor Technology Korea (K4), INC (ATK) | |
| Bump material | | Sn1.8Ag | Sn1.8Ag | |
| Die attach material | Part Number | SCF-5 | SCF-5 | |
| | Conductive | No | No | |
| Under fill material | | NAU-27-1F | NAU-27-1F | |
| Substrate Material | Core Material | E679FGR | E679FGR | E705G |
| | Solder mask | AUS703 | AUS703 | |
| | Process | GX13 | GX13 | GX92 |
| Solder Ball | | SAC305 | SAC305 | |

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity and on-time delivery performance by qualifying an additional bill of materials for PM5456A-FEI, PM5451A-FEI and PM5450A-FEI Microsemi catalog part numbers (CPN) available in 1517L BBGA (40x40x3.22mm) package at ATK assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:October 30, 2021 (date code: 2144)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

| | June 2021 | | | | | > | October 2021 | | | | | > | January 2022 | | | | |
|--------------------------|-----------|--------|--------|--------|--------|---|--------------|----|----|----|----|---|--------------|---|---|---|---|
| Workweek | 2 3 | 2 4 | 2 5 | 2 6 | 2 7 | | 40 | 41 | 42 | 43 | 44 | | 1 | 2 | 3 | 4 | 5 |
| Initial PCN Issue Date | | X | | | | | | | | | | | | | | | |
| Qual Report Availability | | | | | | | | | | | | | | | | X | |
| Final PCN Issue Date | | | | | | | | X | | | | | | | | | |
| Estimated Implementation | | | | | | | | | | | X | | | | | | |

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Affected Catalog Part Numbers (CPN)

PM5456A-FEI

PM5451A-FEI

PM5450A-FEI